TECHNICAL DATA SHEET

HS-2240

High-Temperature Lamp Base Adhesive

Two-part, heat-cured adhesive for bonding, fixing and sealing ceramic lamp bases to quartz glass tubes in high-temperature lighting assemblies.

Product data

Property	Supplied specification
Components / appearance	Part A: grey viscous liquid Part B: white or red powder
Cured appearance	Grey-white or red hard solid
Continuous service temperature	-40 to +600 °C
Short-term peak temperature	Up to +800 °C; validate for the application
Mix ratio by weight, A:B	1:1-2 (1 part A to 1-2 parts B)
Rest time after mixing	4 hours before application, for air release
Use period	Use the mixed material within the same day
Tensile shear strength	≥1.5 MPa after curing at 100 °C for 2 hours
Pressure resistance*	≥5.0 MPa after curing at 100 °C for 2 hours
Standard packaging	1.6 kg/set; 16 kg/carton
Storage / shelf life	At or below 28 °C; RH at or below 70% 12 months, sealed and unopened under specified storage conditions

*The source describes this property as pressure resistance. The test method and specimen geometry are not specified. Strength values relate to the stated test cure; other cure schedules require application validation.

Application areas

Ceramic-to-quartz lamp joints; high-temperature equipment lighting assemblies; quartz heating tube and lamp end assemblies. Evaluate substrates, joint geometry, temperature cycling and sealing requirements on representative parts before production.

1. Prepare surfaces

Keep all bonding surfaces clean, dry and free from oil, dust and other contaminants. Ensure the parts fit correctly before applying adhesive.

2. Weigh, mix and rest

Mix Part A and Part B thoroughly at A:B = 1:1-2 by weight. Allow the mixture to stand for 4 hours to release trapped air before coating or filling. Prepare only the amount needed and use within the same day. Discard material that has formed lumps or hardened.

3. Apply and cure

Process	Temperature and hold time
Standard cure	80-100 °C for 2-4 hours, then cool with the oven
Lower-bubble staged cure	40 °C for 2 hours, then 60 °C for 2-4 hours; cool with the oven
Strength reference condition	100 °C for 2 hours; used for the strength values on page 1

Select and validate the cure process for the joint and assembly. Room-temperature cure is very slow and gives lower strength, so it is not recommended. Allow the adhesive to cure fully before further machining, assembly or performance testing.

Cleaning and moisture control

Wipe away excess uncured adhesive using a clean cloth dampened with water. Mixing containers may be soaked in water for cleaning. Keep cured assemblies protected from prolonged humidity: moisture absorption can reduce bond strength and electrical insulation performance.

Storage and handling

Store sealed in a cool, dry, ventilated area, away from heat, direct sunlight and corrosive gases. Maximum storage temperature: 28 °C. Maximum relative humidity: 70%. Shelf life is 12 months in unopened original packaging under these conditions. Request the current SDS for safe handling and protective equipment guidance.

Prepared from the supplied HS-2240 product specification. Performance depends on the materials, joint design, mixing, cure and service conditions. This TDS does not establish certification for explosion-proof equipment or other regulated assemblies. Confirm suitability by testing before production use.